Pub B1

1. (Amended) A tape carrier package semiconductor device, which has a tape carrier and semiconductor elements that have been packaged on the tape carrier, said tape carrier package semiconductor device comprising:

an insulating tape,

a metal wiring pattern installed on one surface of the insulating tape,

a through hole that is provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,

only a first insulating protective film for insulating and covering the metal wiring pattern and the through hole on the metal-wiring-pattern side,

a second insulating protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side, and

resin sealing peripheral portions where the metal wiring pattern and a semiconductor element are connected;

Q-1

wherein the first and second insulating protective films are made of solder resist whose young's modulus is in the range of 5 kgf/mm^2 to 70 kgf/mm^2, and wherein no insulating protective film other than said first insulating protective film covers the metal wiring pattern and the through hole on the metal wiring pattern side.

Pub B2

Q2

10. (Amended) A liquid crystal panel display, which is provided with a liquid crystal panel and a tape carrier package semiconductor device having a tape carrier and semiconductor elements that have been packaged on the tape carrier so as to drive the liquid crystal panel, wherein said tape carrier comprises:

an insulating tape,

a metal wiring pattern installed on one surface of the insulating tape,

a through hole that is provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,

only a first insulating protective film for insulating and covering the metal wiring pattern and the through hole on the metal-wiring-pattern side,

a second insulating protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side, and

resin for sealing periphery portions at which the semiconductor device and the metal wiring pattern are connected,

wherein the first and second insulating protective films are made of solder resist whose young's modulus is in the range of 5 kgf/mm^2 to 70 kgf/mm^2, and only the first insulating protective film insulates and covers the metal wiring pattern and the through hole on the metal wiring pattern side.

Please add the following new claim:

-- 23 (New) A tape carrier package semiconductor device comprising:

an insulating tape,

a metal wiring pattern on one surface of the insulating tape,

a through hole provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,

only a first insulating solder resist protective film for insulating and covering the metal wiring pattern and the through hole on the metal-wiring-pattern side, and

a second insulating solder resist protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side,

wherein the first and second insulating solder resist protective films are made of solder resist whose young's modulus is in the range of 5 kgf/mm^2 to 70 kgf/mm^2, and no insulating solder resist other than said first insulating solder resist protective film covers the metal wiring pattern and through hole on the metal wiring pattern side. --

REMARKS

This is in response to the Office Action dated December 21, 2000. Non-elected claims 20-22 have been canceled, without prejudice in view of the Restriction Requirement. New claim 23 has been added. Thus, claims 1-19 and 23 are now pending. Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page/s is/are captioned "**Version With Markings To Show Changes Made**."

Independent claims 1 and 10 stand rejected under 35 U.S.C. §102(a) as being allegedly anticipated by the admitted prior art. It is Applicants' understanding that the allegedly "admitted prior art" refers to Figures 7 and 9 of the instant application. This §102(a) rejection is respectfully traversed for at least the following reasons.